

DESCRIPTION

SUITIT® TB6810 is a two-component, low temperature fast curable epoxy adhesive, which is halogen-free, good bonding strength, high toughness, and excellent impact resistance, suitable for most materials bonding, such as metal and ceramics.

PROPERTIES UNCURED

	Part A	Part B
Appearance	Light yellow liquid	Light yellow liquid
Chemical types	Epoxy resin	Modified amines
Density (g/cm ³)	1.11	1.10
Viscosity (mPa.s)	6000-15000	6000-15000

PROPERTIES MIXED

Appearance after mixed Light yellow liquid

Density after mixed (g/cm³) 1.11

Mixing ration (A:B)

Volume ratio 1: 1

Operate time (min 20g@25℃) 5

PERFORMANCE AFTER CURED

(Full cured)

Hardness (shore,D) 80 GB/T2411-1980

Shearing strength for different materials (MPa) GB/T7124-1986

Aluminum 14.8

Steel 15

Copper 13.8

ABS 4.5

PMMA 4.2

Fiberglass 4.8

PVC 4.5

DIRECTION FOR USE

Clean the bonding surface before use (Recommend using), remove the oil stains, and dust of the

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bonding surface. Please do not use alcohol, gasoline or paint cleaner.

If you want to have a high mechanical strength, adhesion to the surface by mechanical polishing, sandblasting or chemical corrosion treatment.

Mix the resin and curing agent proportionally, lay the mixture equalmente on two bonding surfaces, adhesive layer for 0.05mm.

The curing speed depends on the quantity of one-time mixture and ambient temperature, more mixture and higher temperature faster curing.

The remaining unmixed adhesive to be sealed, stored frozen in a cool dry place.

NOTICE

Keep away from children.

The workshop should be adequate ventilation.

Wash with soapy water if on skin.

Wash with a lot of soapy water and then go for doctor if in eyes.

For more information, please refer to MSDS.

PACKAGE

50ml/pail

STORAGE

Store the product in a clean and dry location in unopened containers at 8-28℃

Shelf-life: 24 months

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THEBOND